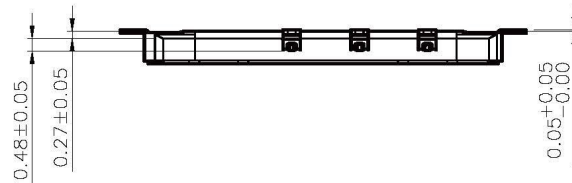


RECOMMENDED P.C.B. LAYOUT
TOLERANCE:±0.05 TOP VIEW

- PCB AREA
- CONNECT AREA
- KEEP OUT AREA

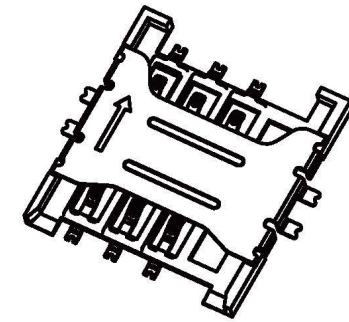


MATERIALS

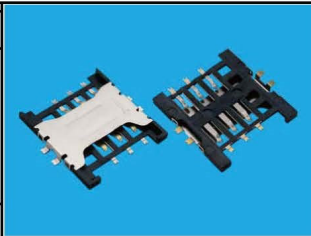
1. HOUSING : THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY,
PLATING : GOLD PLATED ON CONTACT AREA
AND SOLDER TAILS,NICKEL PLATED OVERALL.
3. SHELL : STAINLESS STEEL
PLATING : NICKEL PLATED OVERALL.
GOLD PLATED ON SOLDER TAILS

SPECIFICATION

1. CURRENT RATING : 1.0 A MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :
500V AC R.M.S. FOR ONE MINUTE.
3. INSULATION RESISTANCE : 1000M次MIN. AT 500V DC.
4. CONTACT RESISTANCE : 30m 次MAX.
5. OPERATING TEMPERATURE : -40°C TO +85°C.



		RoHS Compliant		TOLERANCES ARE	
		DRAWING BY CY		X ±	
CHECKED BY GENIUS		UNIT/ mm		.X ± 0.30	
SCALE 1 : 1		DATE		.XX ± 0.20	
SIZE A4		P PROJECTION		.XXX ± 0.10	
www.allconnectors.de		info@allconnectors.de		ANG ±	
Tel.: 0049 711 7009503		Fax: 0049 711 7009504			
70794 Filderstadt - Germany		Kettenerstr. 25			



ORDER INFORMATION			
MISCT-W1212X-06-LF			
SERIES	90°SMT	W/O LOCATING PEG	LEADFREE
PAD TO PAD 12.6mm		HIGH 1.27mm	
DESCRIPTION: SIM card no push 1.27H			